ABSTRACT

In order to provide an adhesive composition for electronic components that is excellent in adhesion durability under long-term high temperature conditions, thermal cyclability, and insulation reliability, designed is an adhesive composition for electronic components containing a thermoplastic resin (a), an epoxy resin (b), a hardener (c), and an organopolysiloxane (d), wherein the glass transition temperature (Tg) after curing is -10°C to 50°C and the rate of change of Tg after heat-treating the composition at 175°C for 1000 hours is 15% or less.